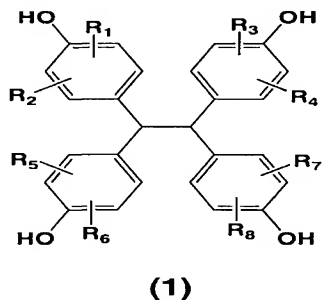


CLAIMS

1. A photosensitive resin composition comprising a resin (A) soluble in an aqueous alkaline solution, a crosslinking agent (B), a photopolymerization initiator (C), and a curing agent (D), wherein the curing agent (D) is an epoxy compound obtained by glycidylating a compound containing not less than 80% of a tetraphenylethane derivative represented by formula (1):

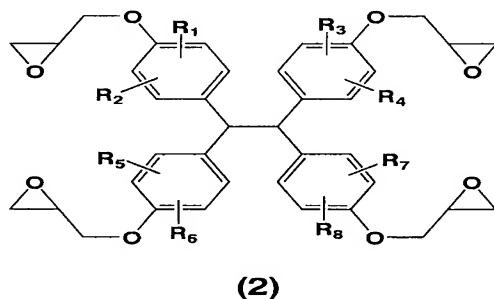


wherein R_1 to R_8 each independently represents a hydrogen atom, a C_1 to C_4 alkyl group, or a halogen atom.

2. The photosensitive resin composition according to Claim 1, wherein the epoxy compound, which is the curing agent (D), is a compound obtained by glycidylating a tetraphenylethane derivative represented by formula (1) wherein each R_1 to R_8 is

a hydrogen atom, and the compound has an epoxy equivalent of 120 to 200 g/equivalent.

3. The photosensitive resin composition according to Claim 1, wherein the epoxy compound, which is the curing agent (D), includes a compound represented by formula (2):



wherein R₁ to R₈ each independently represents a hydrogen atom, a C₁ to C₄ alkyl group, or a halogen atom and the content of the compound in the curing agent (D) is not less than 60 mole percent.

4. The photosensitive resin composition according to claim 1, wherein the curing agent (D) has a softening point or melting point of not less than 80°C.

5. The photosensitive resin composition according to claim 1,

wherein the curing agent (D) has a light transmittance at 400 nm of not less than 10% in a 1 weight percent methyl ethyl ketone solution.

6. The photosensitive resin composition according to claim 1, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (a) having two or more epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, and a polybasic acid anhydride (c).

7. The photosensitive resin composition according to claim 1, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (d) having two epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, a diisocyanate compound (e), a carboxylic acid (f) having two hydroxyl groups per molecule, and, as an optional component, a diol compound (g).

8. A cured product of the photosensitive resin composition according to claim 1.

9. A substrate comprising a layer composed of the cured

product according to Claim 8.

10. An article comprising the substrate according to Claim 9.

11. The photosensitive resin composition according to claim 2, wherein the curing agent (D) has a softening point or melting point of not less than 80°C.

12. The photosensitive resin composition according to claim 2, wherein the curing agent (D) has a light transmittance at 400 nm of not less than 10% in a 1 weight percent methyl ethyl ketone solution.

13. The photosensitive resin composition according to claim 2, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (a) having two or more epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, and a polybasic acid anhydride (c).

14. The photosensitive resin composition according to claim 2, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (d) having two epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, a

diisocyanate compound (e), a carboxylic acid (f) having two hydroxyl groups per molecule, and, as an optional component, a diol compound (g).

15. A cured product of the photosensitive resin composition according to claim 2.

16. A substrate comprising a layer composed of the cured product according to Claim 15.

17. An article comprising the substrate according to Claim 16.

18. The photosensitive resin composition according to claim 3, wherein the curing agent (D) has a softening point or melting point of not less than 80°C.

19. The photosensitive resin composition according to claim 3, wherein the curing agent (D) has a light transmittance at 400 nm of not less than 10% in a 1 weight percent methyl ethyl ketone solution.

20. The photosensitive resin composition according to claim 3, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (a) having two or more epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule,

and a polybasic acid anhydride (c).

21. The photosensitive resin composition according to claim 3, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (d) having two epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, a diisocyanate compound (e), a carboxylic acid (f) having two hydroxyl groups per molecule, and, as an optional component, a diol compound (g).

22. A cured product of the photosensitive resin composition according to claim 3.

23. A substrate comprising a layer composed of the cured product according to Claim 22.

24. An article comprising the substrate according to Claim 23.